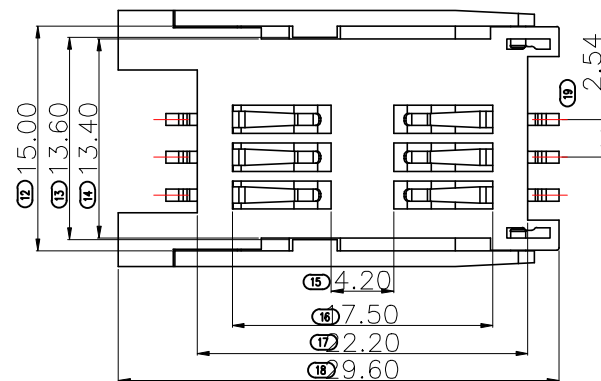
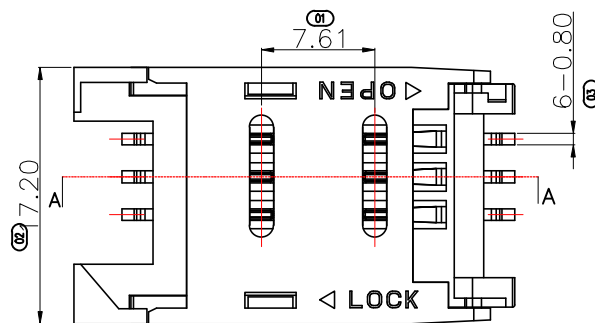


RoHS Compliant



A. Material:

1. Insulator: High temperature thermoplastic
UL94V-0, (BLACK LCP)
2. Pho. Bronze: Plating,
50U" MIN NICKEL UNDERPLATED;
3-8U" GOLD ON THE CONTACT AREA;
100U" TIN PLATING ON SOLDER TAIL

B. Electrical specifications:

Voltage rating: 10 V AC

Current rating: 0.5A

Dielectric strength: 500V AC for 1 minute min

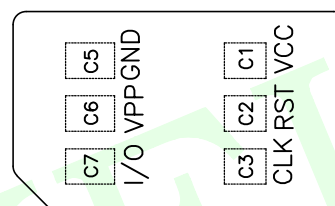
Insulation resistance: 1000 M ohm

Contact resistance: 100 mill.ohm max

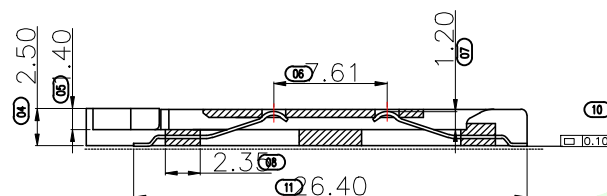
Operation temperature: -25°C to $+95^{\circ}\text{C}$

Product withstanding rff low

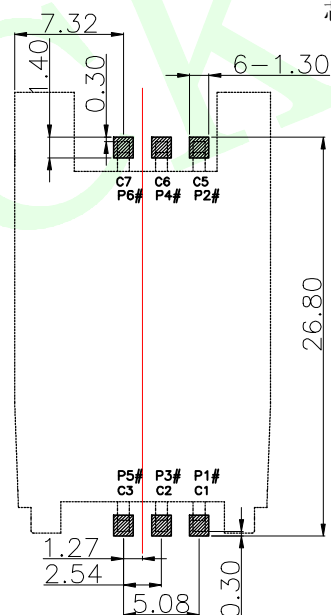
soldering 260°C for 10s



SIM 示意图
芯片面朝下视图



SEC: A-A



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

连晟欣
LCK

产品类别
MS: MINI SIM
SIM: MICRO SIM
NANO: NANO SIM

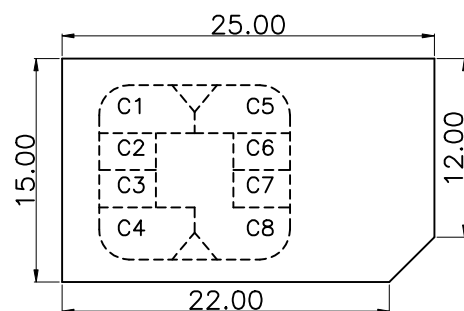
产品高度
H250: 2.50MM

产品PIN位
07: 7PIN

电镀规格
G: gold flash
G1: 1U
G3: 3U
(以此类推)

包装方式
L: 圆盘

有柱无柱
Y: 有柱
W: 无柱



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED MATA MASK T=0.12MM

MEASURE POINT:

QUADRANT POINT

TANGENCY POINT

TANGENT POINT
INTERSECTION POINT

UNLESS OTHERWISE
SPECIFIED, TOLERANCE:

X.	± 0.25
X.x	± 0.20
X.xx	± 0.15
ANGULAR	$\pm 3^{\circ}$

QP

II
IP



DESIGN	Andy	DATE	2014.12.24	TITLE: MINI SIM PUSH 6+1P 有柱脚距5.0 右开关后脚		
CHECKED		DATE				
APPROVED		DATE				
PART NO: LCK-MS-207H25007-WLG				REV: 04	SCALE: 1:1	UNIT: mm
DRAWING NO: 102022211				SIZE: A4	SHEET: 1/1	 